

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wei-Chieh Huang</td> <td>12/21/2011</td> </tr> <tr> <td>Hung Chang Hsieh</td> <td>12/21/2011</td> </tr> </tbody> </table>		Name	Execution Date	Wei-Chieh Huang	12/21/2011	Hung Chang Hsieh	12/21/2011
Name	Execution Date						
Wei-Chieh Huang	12/21/2011						
Hung Chang Hsieh	12/21/2011						
RECEIVING PARTY DATA							
Name:	Taiwan Semiconductor Manufacturing Company Ltd.						
Street Address:	No. 8, Li-Hsin Rd. 6						
Internal Address:	Science-Based Industrial Park						
City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13334266</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13334266		
Property Type	Number						
Application Number:	13334266						
CORRESPONDENCE DATA							
Fax Number:	(214)200-0853						
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ATTORNEY DOCKET NUMBER:	2011-1089/24061.1999						
NAME OF SUBMITTER:	David M. O'Dell						
Total Attachments: 2 source=1999Assignment#page1.tif source=1999Assignment#page2.tif							

OP \$40.00 13334266

Docket No.: 2011-1089 / 24061.1999
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Wei-Chieh Huang of No. 186, Zhongfu Road
Hualien City, Hualien County 970, Taiwan, R.O.C.
- (2) Hung Chang Hsieh of 9F, No. 72-12, Lane 531, Sec. 1, Kung-Fu Road
Hsin-Chu City, Taiwan, R.O.C.

have invented certain improvements in

METHOD AND APPARATUS FOR DRYING A WAFER

for which we have filed an application for Letters Patent of the United States of America on
December 22, 2011, as U.S. Serial No. 13/334,266; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Wei-Chieh Huang

Residence Address: No. 186, Zhongfu Road
Hualien City, Hualien County 970, Taiwan, R.O.C.

Dated: 2011.12.21

Wei-Chieh Huang
Inventor Signature

Inventor Name: Hung Chang Hsieh

Residence Address: 9F, No. 72-12, Lane 531, Sec. 1, Kung-Fu Road,
Hsin-Chu City, Taiwan, R.O.C.

Dated: 2011.12.21

Hung-Chang Hsieh
Inventor Signature